

2SJ386

Silicon P Channel MOS FET

REJ03G0861-0200

(Previous: ADE-208-1195)

Rev.2.00 Sep 07, 2005

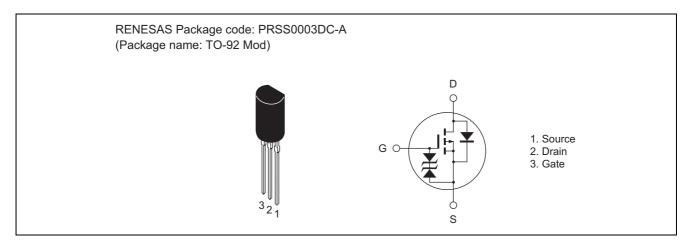
Description

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source
- Suitable for Switching regulator, DC-DC converter

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Value | Unit |
|---|-------------------------------|-------------|------|
| Drain to source voltage | V _{DSS} | -30 | V |
| Gate to source voltage | V_{GSS} | ±20 | V |
| Drain current | I _D | -3 | A |
| Drain peak current | I _{D (pulse)} Note 1 | -5 | A |
| Body to drain diode reverse drain current | I _{DR} | -3 | Α |
| Channel dissipation | Pch | 0.9 | W |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

Note: 1. PW \leq 10 μ s, duty cycle \leq 1%

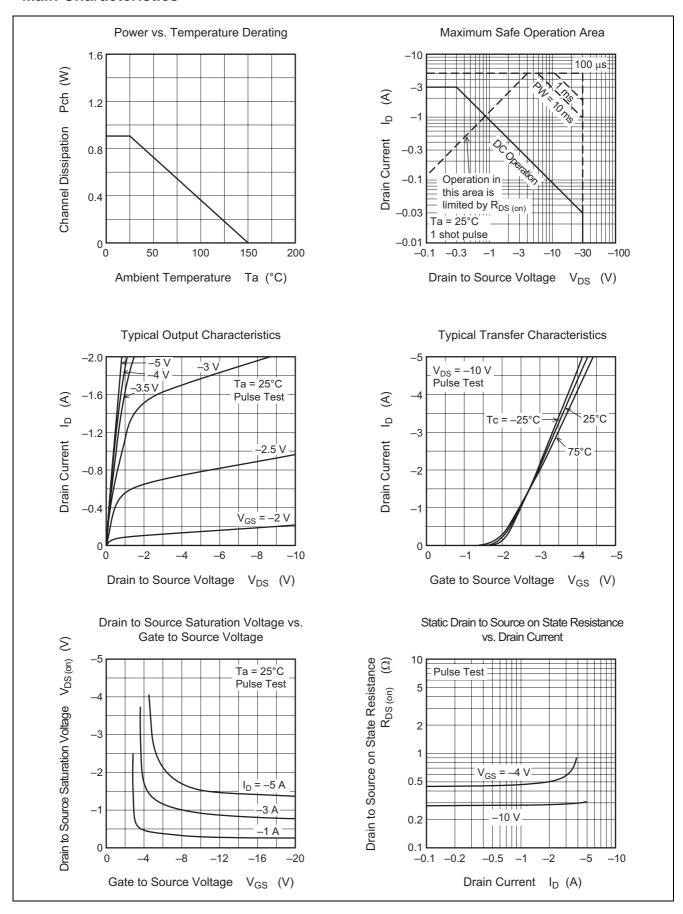
Electrical Characteristics

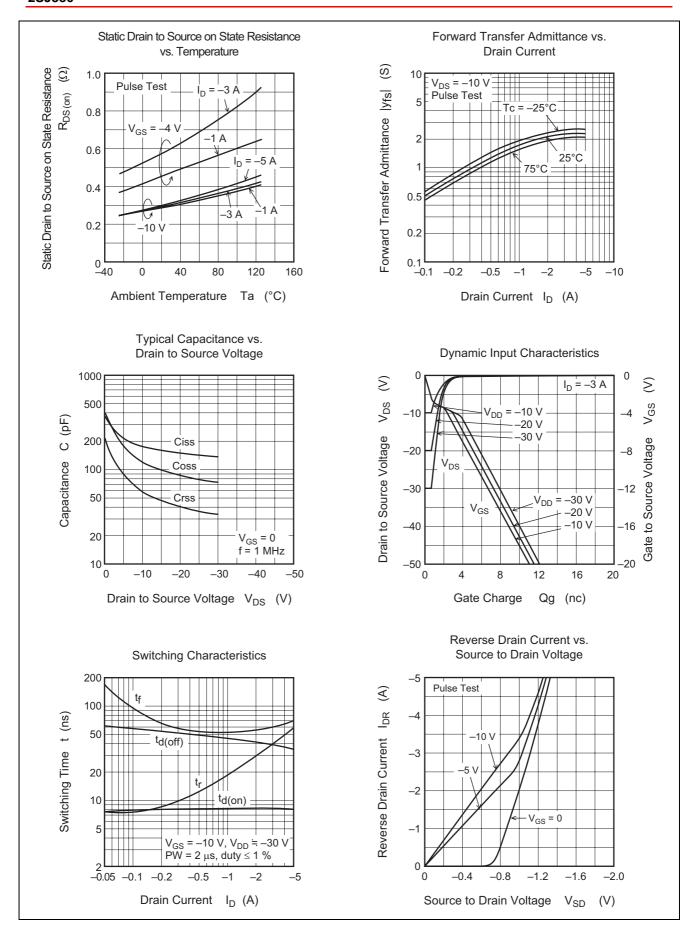
 $(Ta = 25^{\circ}C)$

| Item | Symbol | Min | Тур | Max | Unit | Test Conditions |
|--|-----------------------|------|------|------|------|--|
| Drain to source breakdown voltage | V _{(BR) DSS} | -30 | _ | _ | V | $I_D = -10 \text{ mA}, V_{GS} = 0$ |
| Gate to source breakdown voltage | V _{(BR) GSS} | ±20 | _ | _ | V | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$ |
| Gate to source leak current | I _{GSS} | _ | _ | ±10 | μΑ | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$ |
| Zero gate voltage drain current | I _{DSS} | _ | _ | -10 | μΑ | $V_{DS} = -24 \text{ V}, V_{GS} = 0$ |
| Gate to source cutoff voltage | V _{GS (off)} | -1.0 | _ | -2.5 | V | $I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$ |
| Static drain to source on state resistance | R _{DS (on)} | _ | 0.3 | 0.4 | Ω | $I_D = -2 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 2}}$ |
| | R _{DS (on)} | _ | 0.55 | 0.8 | Ω | $I_D = -2 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 2}}$ |
| Forward transfer admittance | y _{fs} | 1.0 | 1.7 | _ | S | $I_D = -1 A, V_{DS} = -10 V^{Note 2}$ |
| Input capacitance | Ciss | _ | 177 | _ | pF | $V_{DS} = -10 \text{ V}$ |
| Output capacitance | Coss | _ | 120 | _ | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | Crss | _ | 59 | _ | pF | f = 1 MHz |
| Turn-on delay time | t _{d (on)} | _ | 8 | _ | ns | $I_D = -2 A$ |
| Rise time | t _r | _ | 28 | _ | ns | $V_{GS} = -10 \text{ V}$ |
| Turn-off delay time | t _{d (off)} | _ | 45 | _ | ns | $R_L = 15 \Omega$ |
| Fall time | t _f | _ | 60 | _ | ns | |

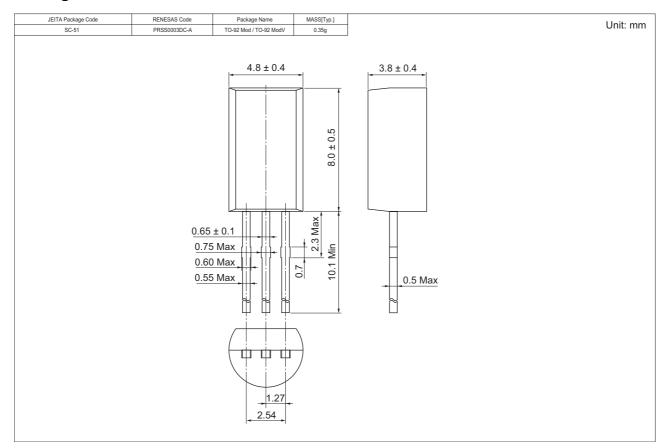
Note: 2. Pulse test

Main Characteristics





Package Dimensions



Ordering Information

| Part Name | Quantity | Shipping Container |
|------------|----------|--------------------|
| 2SJ386TZ-E | 2500 pcs | Taping |

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